MSKSEMI















ESD

TVS

TSS

MOV

GDT

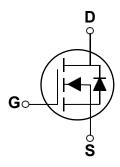
PLED

Broduct data sheet





SOT-23



Features

- 30V, 2.0 A, $RDS(ON) = 300m\Omega@VGS = 4.5V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

Applications

- Notebook
- Load Switch
- LED applications

BVDSS	RDSON	ID
30V	300m $Ω$	2.0A

Absolute Maximum Ratings Tc=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	30	V
V _G s	Gate-Source Voltage	±12	V
I-	Drain Current – Continuous (T _C =25°C)	2.0	Α
ID	Drain Current – Continuous (Tc=100°C)	1.2	Α
I _{DM}	Drain Current – Pulsed ¹	4.0	Α
D	Power Dissipation (Tc=25°C)	1.0	W
P _D	Power Dissipation – Derate above 25°C	0.012	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	℃

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Unit
Reja	Thermal Resistance Junction to ambient		80	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =1mA		0.06		V/°C
	Dunin Course I calcone Current	V _{DS} =30V , V _{GS} =0V , T _J =25°C			1	uA
IDSS	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =125°C			10	uA
Igss	Gate-Source Leakage Current	V _{GS} =±12V , V _{DS} =0V			±100	nA

On Characteristics

R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =4.5V , I _D =2A		200	400	mo	
NDS(ON)	Static Dialii-Source Off-Nesistance	V _{GS} =2.5V , I _D =1A		400	600	mΩ	
$V_{GS(th)}$	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA		0.8	1.2	٧	
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient			-3		mV/°C	
gfs	Forward Transconductance	V _{DS} =10V , I _S =3A		7		S	

Dynamic and switching Characteristics

•	•				
Qg	Total Gate Charge ^{2, 3}			8.4	
Qgs	Gate-Source Charge ^{2, 3}	V_{DS} =10V , V_{GS} =4.5V , I_{D} =1A		1	 nC
Q_{gd}	Gate-Drain Charge ^{2, 3}			2.2	
$T_{d(on)}$	Turn-On Delay Time ^{2, 3}			4.5	
Tr	Rise Time ^{2, 3}	V_{DD} =10V , V_{GS} =4.5V , R_{G} =25 Ω		13	
T _{d(off)}	Turn-Off Delay Time ^{2, 3}	I _D =1A		27	 nS
Tf	Fall Time ^{2, 3}			8.3	
Ciss	Input Capacitance			695	
Coss	Output Capacitance	V _{DS} =10V , V _{GS} =0V , F=1MHz		45	 pF
Crss	Reverse Transfer Capacitance			36	
Rg	Gate resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz		1.5	 Ω

Drain-So						
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current	V _G =V _D =0V , Force Current			2.0	Α
lsм	Pulsed Source Current	VG-VD-0V , Force Current			4.0	Α
VsD	Diode Forward Voltage	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V

Note:

- 1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
- 2. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 3. Essentially independent of operating temperature.





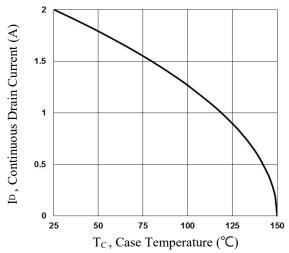


Fig.1 Continuous Drain Current vs. Tc

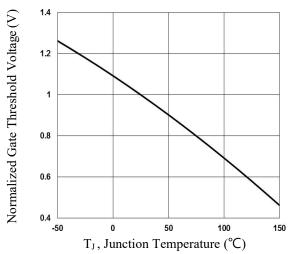


Fig.3 Normalized V_{th} vs. T_J

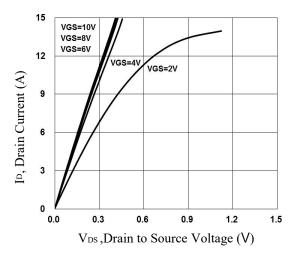


Fig.5 Typical Output Characteristics

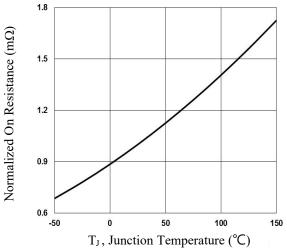


Fig.2 Normalized RDSON vs. T_J

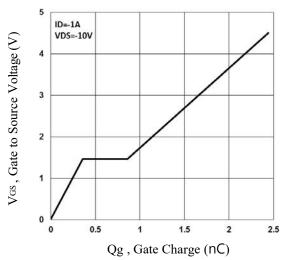


Fig.4 Gate Charge Waveform



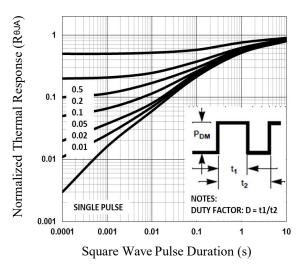


Fig.6 Normalized Transient Impedance

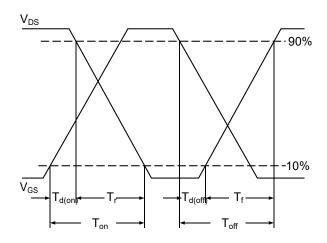


Fig.8 Switching Time Waveform

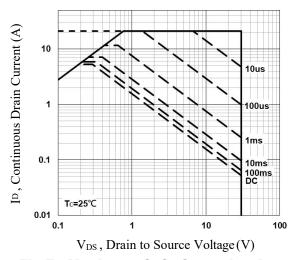


Fig.7 Maximum Safe Operation Area

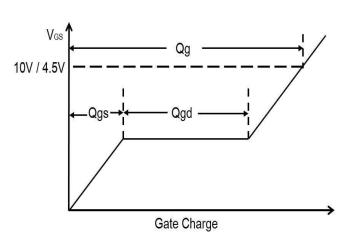
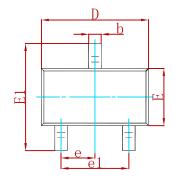
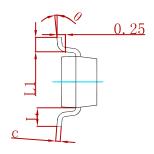


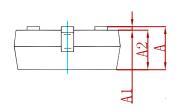
Fig.9 Gate Charge Waveform



PACKAGE MECHANICAL DATA

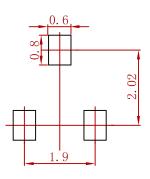






Symbol	Dimensions	Dimensions In Millimeters		s In Inches
Symbol	Min	Max	Min	Max
Α	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
С	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
Е	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
е	0.950 TYP		0.037	7 TYP
e1	1.800	2.000	0.071	0.079
L	0.550) REF	0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

Suggested Pad Layout



- 1.Controlling dimension:in millimeters.2.General tolerance:± 0.05mm.3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
FDV303N	SOT-23	3000



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